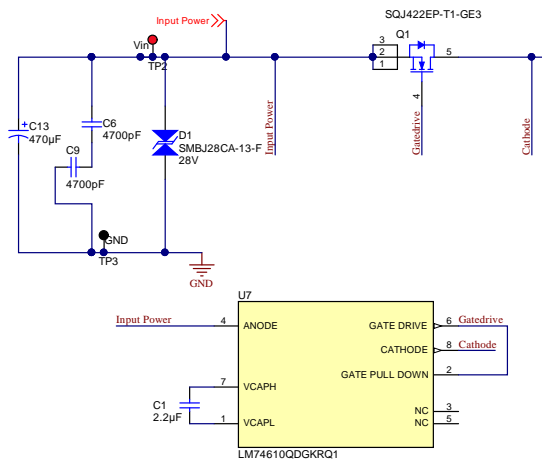
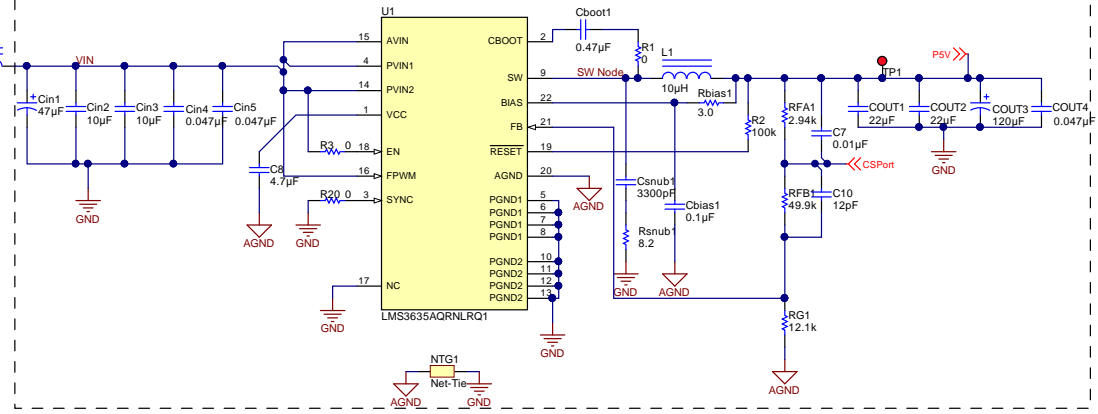
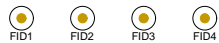


LM74610 - Reverse Battery Protection Smart Diode



LMS3635 - 3.5A Buck Regulator





PCB Number: TIDA-01432
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer



Variant/Label Table	
Variant	Label Text
001	TIDA-01432

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

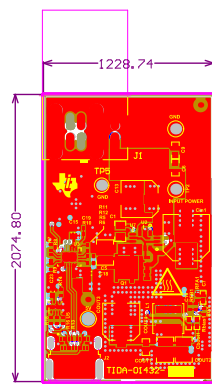
Orderable: EVM_orderable	Designed for: Not for Public Release	Mod. Date: 7/24/2017
TID #: NA	Project Title: TIDA-01432	
Number: TIDA-01432 Rev: E1	Sheet Title:	Sheet: 3 of 3
Drawn By: H.Bovenz	File: TIDA-01432 E1_Hardware_SchDoc	Contact: http://www.ti.com/support

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Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlau				
2	Top Solder	Solder Resist	0.40mil	3.8	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	6.00mil	4.8	
5	Signal Layer 1	Copper	1.40mil		
6	Dielectric2		44.00mil	4.2	
7	Signal Layer 2	Copper	1.40mil		
8	Dielectric 3	Copper	6.00mil	4.2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.8	
11	Bottom Overlau				

- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 8 MIL
 MIN. VIA PAD SIZE: 16 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC DRILL FILES
 PTH COPPER THICKNESS: 20-30 um OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN OTHER _____
 MATTE SEMI-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIG
 IM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

REVISIONS	DATE	BY	DESCRIPTION	APPROVED	DATE	BY	DESCRIPTION	APPROVED	DATE	BY	DESCRIPTION
1	6/8/2017	HT	INITIAL RELEASE								

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PROJECT TITLE: TIDA-01432	DESIGNED FOR: Not for Public Release
FILE NAME: TIDA-01432_E1.PcbDoc	ENGINEER: H. Bovenzi
SCALE: 1.00	LAYOUT BY: Bovenzi/Clanin
	ALTIM DESIGNER VERSION: 17.1.5.472

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